

General Description

The WSC80P03 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSC80P03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

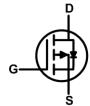
BVDSS	RDSON	ID
-30V	5.4mΩ	-75A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO-251 Pin Configuration





Absolute Maximum Ratings

	Rating			
Symbol	Parameter	10s	Steady State	Units
V_{DS}	Drain-Source Voltage		30	V
V_{GS}	Gate-Source Voltage	<u>±</u>	20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-	75	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹	-1	-60	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-22	-18	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-18	-14	Α
I _{DM}	Pulsed Drain Current ²	-280		Α
EAS	Single Pulse Avalanche Energy ³	415		mJ
I _{AS}	Avalanche Current	-58		Α
P _D @T _C =25°C	Total Power Dissipation ⁴	50		W
P _D @T _A =25℃	Total Power Dissipation ⁴	5	2.5	W
T _{STG}	Storage Temperature Range	-55 t	-55 to 175	
T _J	Operating Junction Temperature Range	-55 t	-55 to 175	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹		62	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		25	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		2.4	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃ , I _D =-1mA		-0.018		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-30A		5.4	9	m 0
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-15A		8.9	15	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/ - 250A	-1.5	-1.8	-3.0	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		5.04		mV/℃
	Drain Source Loakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_J =55 $^{\circ}$ C			5	- uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-20A		36		S
Q_g	Total Gate Charge (-4.5V)	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-24A		93		
Q_{gs}	Gate-Source Charge			15		nC
Q_{gd}	Gate-Drain Charge			19		
T _{d(on)}	Turn-On Delay Time			38		
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		17		no
$T_{d(off)}$	Turn-Off Delay Time	R _G =3.3Ω, I _D =-15A ,RL=0.62Ω		139		– ns –
T _f	Fall Time			37		
C _{iss}	Input Capacitance			5554		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		761		pF
C _{rss}	Reverse Transfer Capacitance			435		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-30A	120			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-75	Α
I _{SM}	Pulsed Source Current ^{2,6}				-280	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V
t _{rr}	Reverse Recovery Time	IF=-15A,dI/dt=100A/µs, T _J =25℃		33		nS
Q_{rr}	Reverse Recovery Charge			18		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH, I_{AS} =-30A
- 4.The power dissipation is limited by 150 $^{\circ}\mathrm{C}$ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

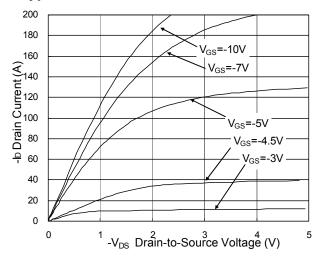


Fig.1 Typical Output Characteristics

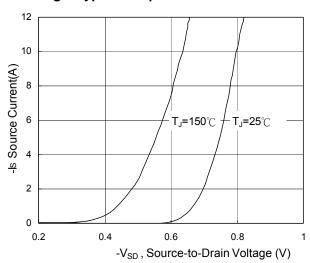


Fig.3 Forward Characteristics Of Reverse

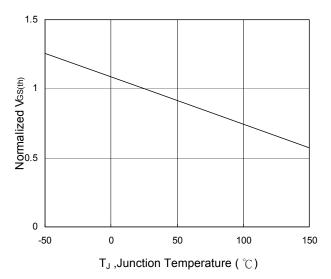


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

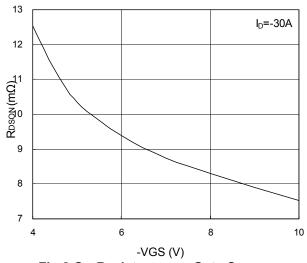


Fig.2 On-Resistance v.s Gate-Source

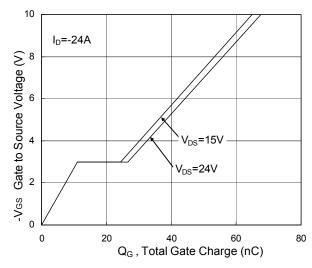


Fig.4 Gate-Charge Characteristics

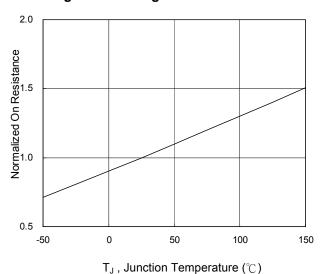
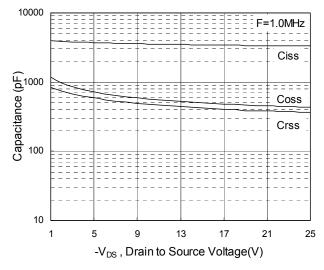


Fig.6 Normalized R_{DSON} v.s T_J





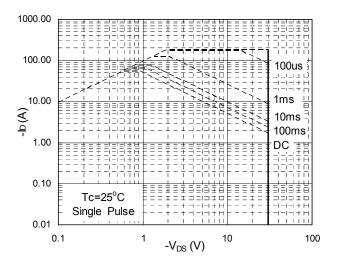


Fig.7 Capacitance

Fig.8 Safe Operating Area

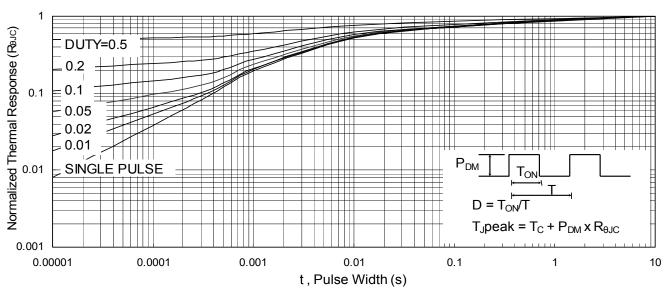


Fig.9 Normalized Maximum Transient Thermal Impedance

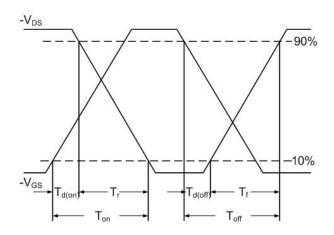


Fig.10 Switching Time Waveform

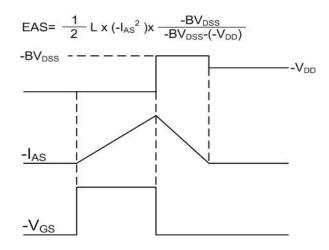


Fig.11 Unclamped Inductive Switching Waveform



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